

IN THE SPECIFICATION/ABSTRACT:

Please rewrite the paragraph at page 6, line 19 to page 7, line 1, so that it reads as follows:

As shown in Fig. 1, the heat radiation structure of the semiconductor device according to the first embodiment of the invention of the present application includes a substrate 200 on which the semiconductor device ~~10~~ 100 is mounted. A wiring 210 electrically connected to the mounted semiconductor device 100 is provided in the surface 201 of the substrate 200. Owing to the wiring 210, the semiconductor device 100 is electrically connected to other electronic parts and the like packaged on the substrate 200.

Please rewrite the paragraph at page 8, lines 5-17, so that it reads as follows:

In the present embodiment, the semiconductor device 100 makes use of the packaged semiconductor element 110. As the package, a wafer level chip size package (hereinafter called "WCSP") is used. A description will now be made of the WCSP. The packaging is adopted such that a wafer formed with a plurality of semiconductor elements is sealed with a resin in a wafer state and thereafter the wafer is cut to ~~bring it into fractionalization every~~ divide it into semiconductor elements. The packaging is characterized in that the size of each semiconductor element and the size of each package are almost identical to each other. Attention has recently been given to it as a package adaptable to the demand for a reduction in size.

Please rewrite the Abstract, on page 31 of the application, so that it reads as shown on a separate page that is attached to this Amendment.